SOOS010 D2969, NOVEMBER 1986

- Gallium Arsenide Phosphide LED Optically Coupled to an Integrated Circuit Detector
- Compatible with TTL and LSTTL Inputs
- Low input Current Required for On-State Output . . .5 mA Max
- High-Voltage Electrical
 Insulation . . . 3000 V DC Min

description

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The HCPL2630 is a dual optocoupler designed for use in high-speed digital interfacing applications that require high-voltage isolation between the input and output. Applications include line receivers, microprocessors or computer interface, and other control systems.

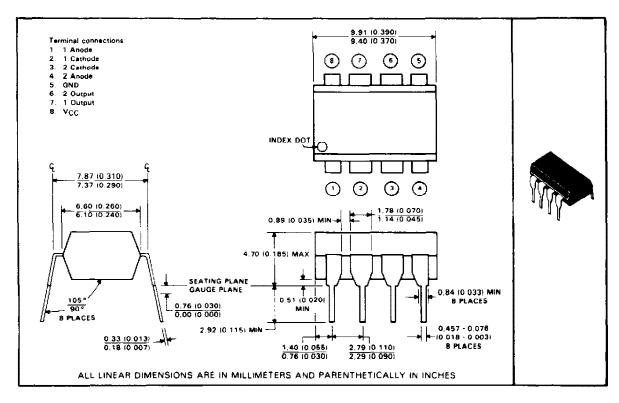
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Each channel of the HCPL2630 optocoupler consists of a GaAsP light-emitting diode and an integrated light detector composed of a photodiode, a high-gain amplifier, and a Schottky-clamped open-collector output transistor. An input diode forward current of 5 milliamperes will switch the output transistor low, providing an on-state drive current of 13 milliamperes (eight 1.6-milliampere TTL loads).

The device is mounted in a standard 8-pin dual-in-line plastic package.

The HCPL2630 is characterized for operation over the temperature range of 0°C to 70°C.

mechanical data



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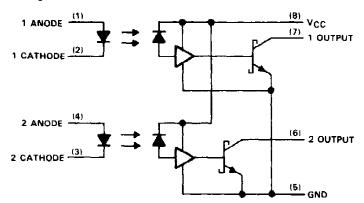
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TEXAS

- Directly Interchangeable with Hewlett Packard HCPL2630
- UL Recognized . . . File Number E65085

High-Speed Switching . . . 75 ns Max

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC}	7 V
Reverse input voltage	
Output voltage	
Peak forward input current, each channel (≤1 ms duration)	30 mA
Average forward input current, each channel	15 mA
Output current, each channel	16 mA
Output power dissipation	85 mW
Storage temperature range	- 55°C to 125°C
Operating free-air temperature range	0°C to 70°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Output supply voltage (see Note 1)	4.5	5	5.5	V
¹ F(on)	Input forward current to turn output on	6.3		15	mA
IF(off)	Input forward current to turn output off	0	<u></u>	250	μA
ΊOL	Low-level (on-state) output current			13	mA
TA	Operating free-air temperature	0		70	°C

NOTE 1: All voltage values are with respect to GND (pin 5).



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

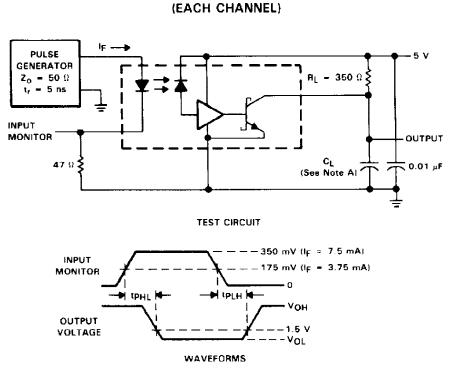
PARAMETER		TEST CONDITIONS		MIN TYP	MAX	UNIT
VF	Input forward voltage	l _F = 10 mA,	$T_A = 25 °C$	1.6	1,75	V
αVF	Temperature coefficient of forward voltage	I _F = 10 mA		- 1.8	_	mV/°C
VBR	Input reverse breakdown voltage	I _R = 10 μA.	$T_A = 25 ^{\circ}C$	5		l v
VOL	Low-level output voltage	$V_{CC} = 5.6 V,$ $I_{OL} = 13 mA$	lp = 5 mA,	0.23	0.6	v
юн	High-level output current	V _{CC} = 5.5 V, I _F = 250 μA	V _O = 5.5 V,		250	μΑ
ЮСн	Supply current, high-level output	V _{CC} - 5.5 V.	lF = 0	20	30	mA
ICCL	Supply current, low-level output	$V_{\rm CC} = 5.5 V_{\rm c}$	I _F = 10 mA	26	36	mA
I ₁₁	Input-input insulation leakage current	V _{II} ≕ 500 V. T _A ≈ 25°C See Note 2		0,005	·	μΑ
li0	input-output insulation leakage current	V _{IO} = 3000 V. T _A ≠ 25 °C. See Note 1			1	Ац
711	Input-input resistance	V _{II} ≕ 500 V, See Note 2	T _A ≈ 25°C,	1011		Ω
10	input-output resistance	V _{IO} = 500 V. See Note 1	T _A = 25°C,	1012		Ω
Ci	Input capacitance	Vp = 0,	f = 1 MHz	60		pF
C _{ii}	Input input capacitance	V _F = 0,	f = 1 MHz	0.25		рF
cio	Input-output capacitance	f = 1 MHz. See Note 1	T _A = 25°C.	0.6		pF

[†] All typical values are at $V_{CC} = 5 V$, $T_A = 25 \,^{\circ}$ C. NOTES = 1. These parameters are measured between pins 1, 2, 3, and 4 shorted together and pins 5, 6, 7, and 8 shorted together 2. These parameters are measured between pins 1 and 2 shorted together and pins 3 and 4 shorted together.

switching characteristics at V_{CC} = 5 V, T_A = $25 \,^{\circ}$ C

PARAMETER		TEST CONDITIONS			TYP	MAX	UNIT
^T PLH	Propagation delay time, low-to-high-level output, from LED input	l _F - 7.5 mA, CL = 15 pF,	R _L → 350 Ω. See Figure 1	1	42	75	ns
^t PHL	Propagation delay time, high-to-low level output, from LED input	l _F = 75 mA, C _L = 15 pF,	R _L = 350 Ω. See Figure 1		42	75	nŝ
t _r	Rise time	l _F · 7.5 mA, C _L = 15 pF	$R_L = 350 \Omega$,		20		ns
t _f	Fall time	lp = 7.5 mA, CL = 15 pF	R _L = 350 Ω,		30		ns
<mark>dVCM</mark> (H	Common-mode input transient immunity, high-level output	$\Delta V_{CM} = 10 V,$ R _L = 350 Ω , See Note 3 and 6			50		V/µs
dVCM dt (L)	Common-mode input transient immunity, low-level output	$\Delta V_{CM} = -10 V$ $R_{L} = 350 \Omega,$ See Note 3 and f			- 150		V/µs

NOTE 3: Common-mode input transient immunity, high-level output, is the maximum rate of rise of the common-mode input voltage that does not cause the output voltage to drop below 2 V. Common-mode input transient immunity, low-level output, is the maximum rate of fall of the common-mode input voltage that does not cause the output voltage to rise above 0.8 V.

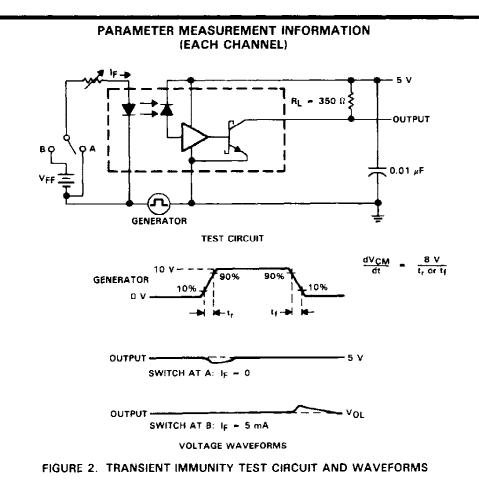


PARAMETER MEASUREMENT INFORMATION

NOTE A: $C_{\rm L}$ is approximately 15 pF, which includes probe and stray wiring capacitances.

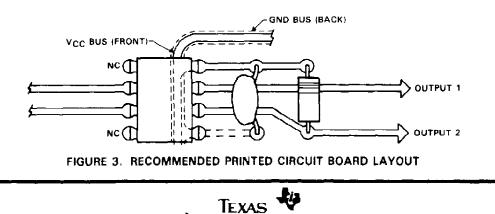
FIGURE 1. TPLH AND TPHL FROM LED INPUT TEST CIRCUIT AND WAVEFORMS



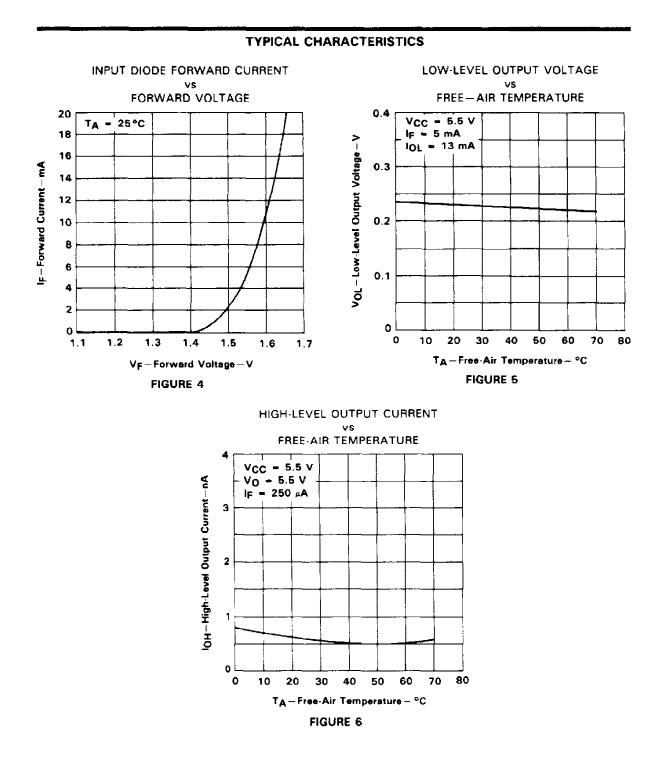


TYPICAL APPLICATION INFORMATION

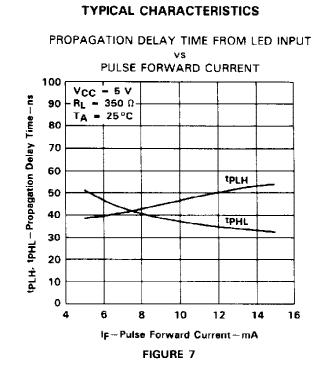
A ceramic capacitor (0.01 μ F to 0.1 μ F) should be connected between pins 8 and 5 to stabilize the highgain amplifier. The total lead length between the capacitor and the optocoupler should not exceed 20 mm (0.8 inches). Failure to provide a bypass capacitor may result in impaired switching characteristics.

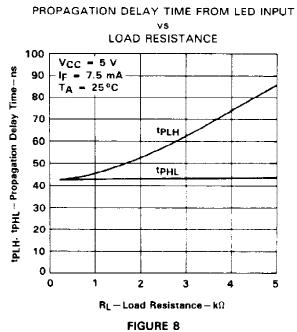


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TEXAS A

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
HCPL2630	OBSOLETE	PDIP	Ν	8	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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